General Purpose NPN Epitaxial Planar Transistor

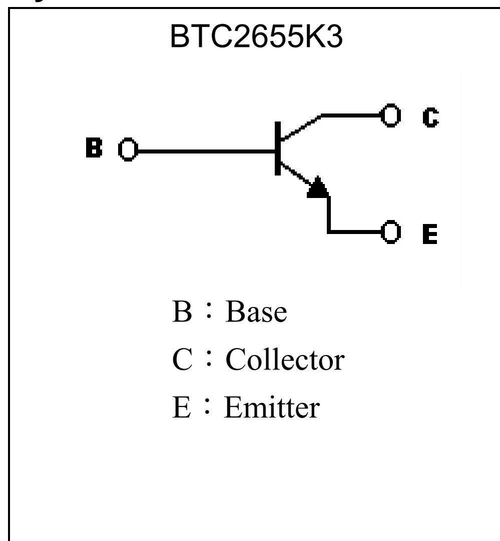
BTC2655K3

BV_{CEO}	60V
I_C	2A
$R_{CESAT(max)}$	300mΩ

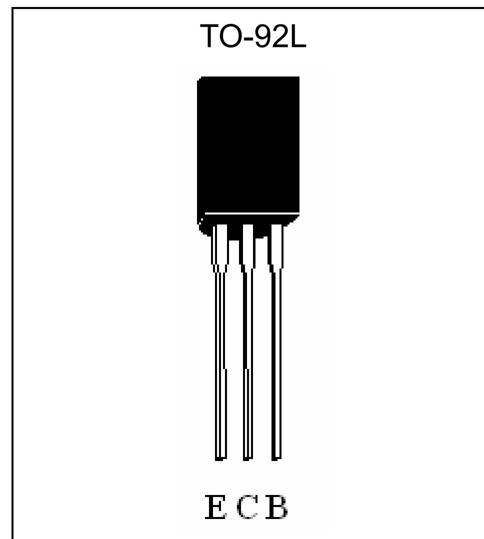
Features

- High breakdown voltage, $BV_{CEO} \geq 60V$
- Large continuous collector current capability
- Low collector saturation voltage
- Pb-free lead plating package

Symbol

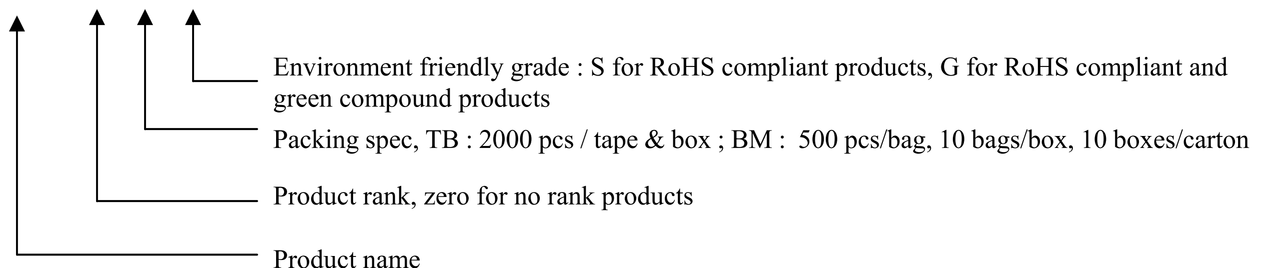


Outline



Ordering Information

Device	Package	Shipping
BTC2655K3-0-TB-G	TO-92L (Pb-free lead plating and halogen-free package)	2000 pcs / tape & box
BTC2655K3-0-BM-G	TO-92L (Pb-free lead plating and halogen-free package)	500 pcs / bag, 10 bags/box, 10 boxes/carton



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	120	V
Collector-Emitter Voltage	V_{CEO}	60	V
Emitter-Base Voltage	V_{EBO}	7	V
Collector Current (DC)	I_C	2	A
Collector Current (pulse)	I_{CP}	5 (Note)	A
Base Current	I_B	0.5	A
Power Dissipation	P_D	900	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	139	°C/W
Operating Junction and Storage Temperature Range	Tj ; Tstg	-55~+150	°C

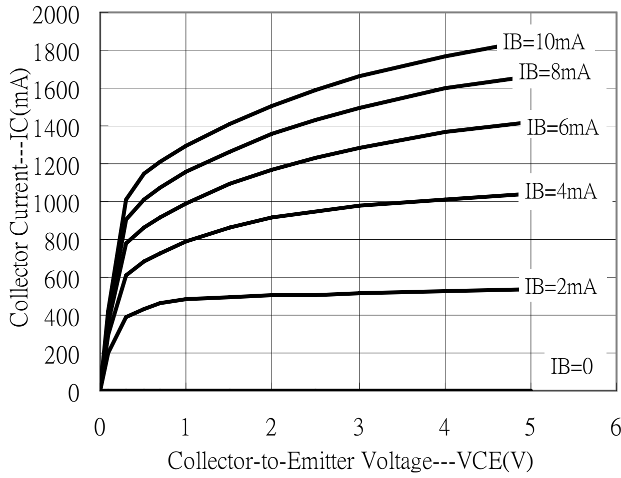
Note : Pulse test, pulse width≤300μs, duty cycle≤2%

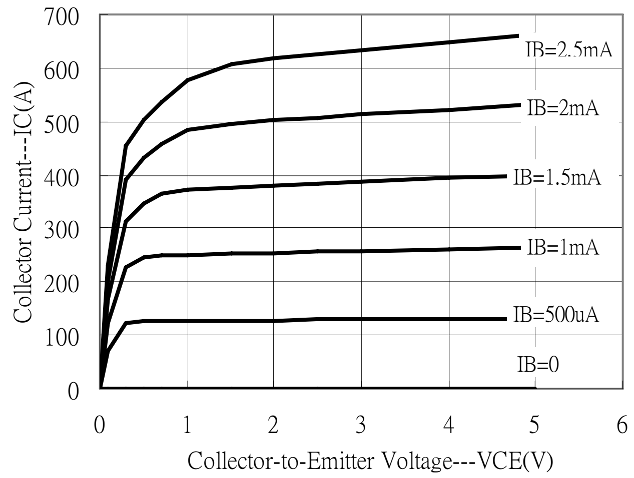
Characteristics (Ta=25°C)

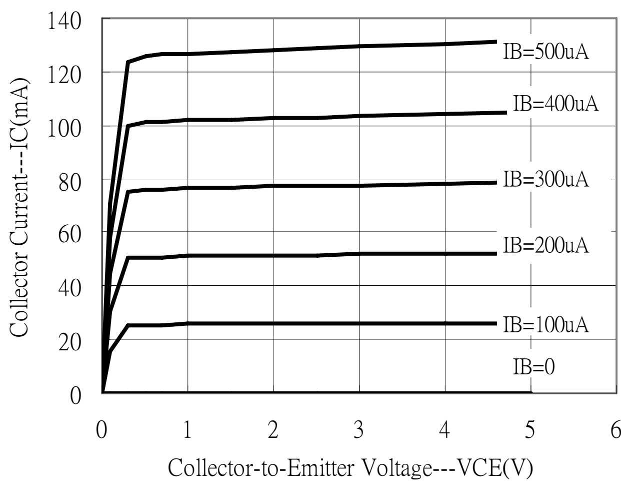
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	120	-	-	V	I_C=50μA
BV_{CEO}	60	-	-	V	I_C=1mA
BV_{EBO}	7	-	-	V	I_E=50μA
I_{CBO}	-	-	100	nA	V_{CB}=120V
I_{EBO}	-	-	100	nA	V_{EB}=7V
*$V_{CE(sat)}$	-	100	300	mV	I_C=1A, I_B=50mA
*$R_{CE(sat)}$	-	100	300	mΩ	I_C=1A, I_B=50mA
*$V_{CE(sat)}$	-	-	350	mV	I_C=1A, I_B=20mA
*$V_{BE(sat)}$	0.5	0.9	1.2	V	I_C=1A, I_B=50mA
*h_{FE} 1	200	-	400	-	V_{CE}=2V, I_C=500mA
*h_{FE} 2	80	-	-	-	V_{CE}=2V, I_C=1.5A
f_T	-	250	-	MHz	V_{CE}=2V, I_C=300mA, f=100MHz
Cob	-	13	-	pF	V_{CB}=10V, I_E=0A,f=1MHz
ton	-	40	-	ns	V_{CC}=30V, I_C=1A, I_B1=-I_B2=33mA, R_L=30Ω
tstg	-	500	-		
tf	-	120	-		

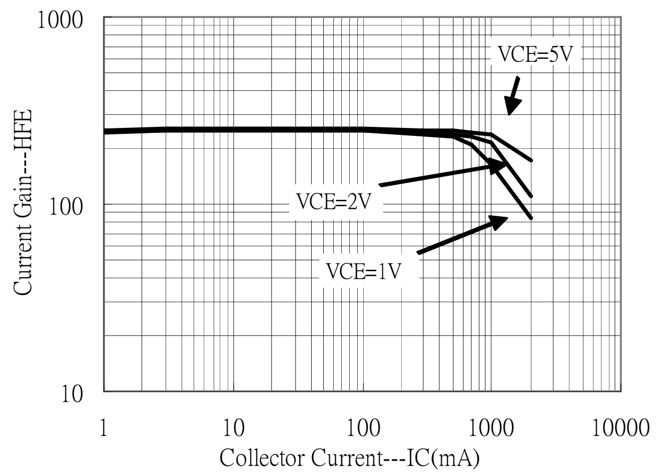
*Pulse Test: Pulse Width ≤300μs, Duty Cycle≤2%

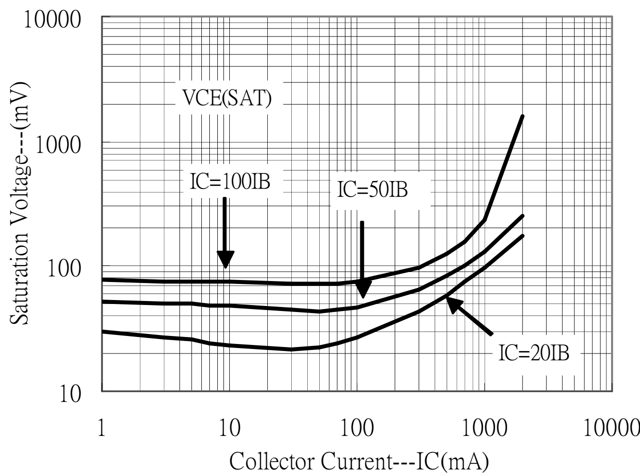
Typical Characteristics

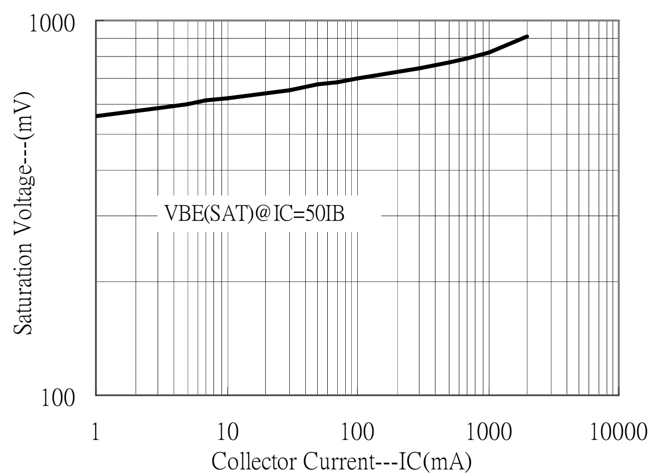




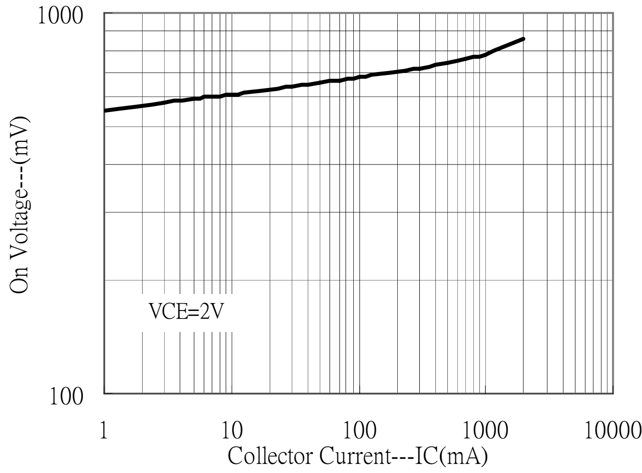


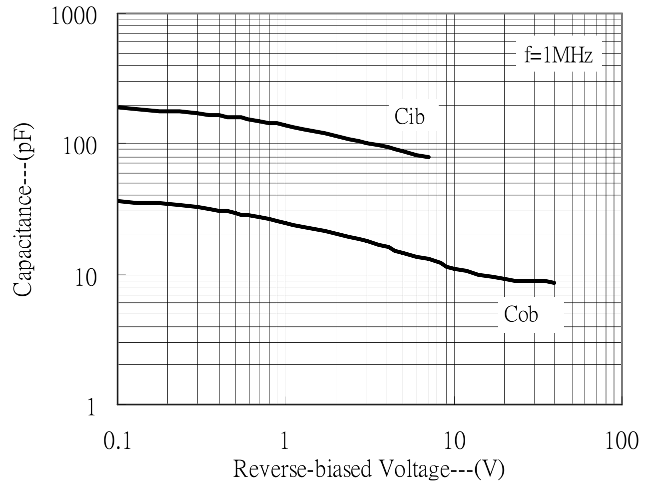


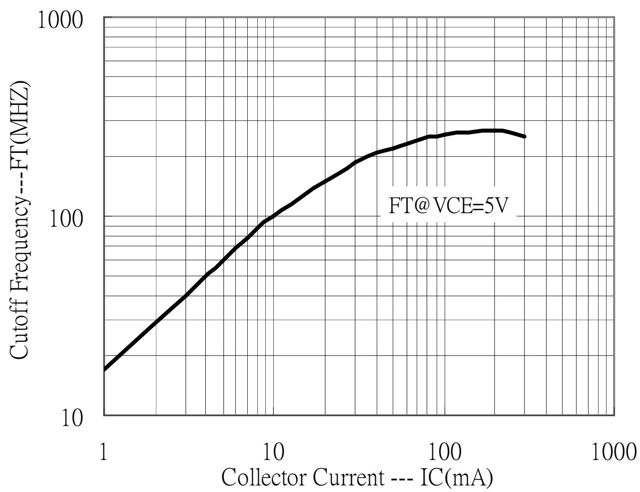


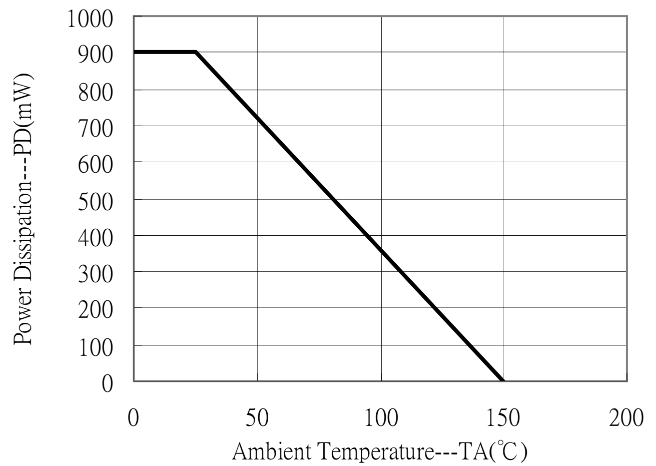


Characteristic Curves(Cont.)

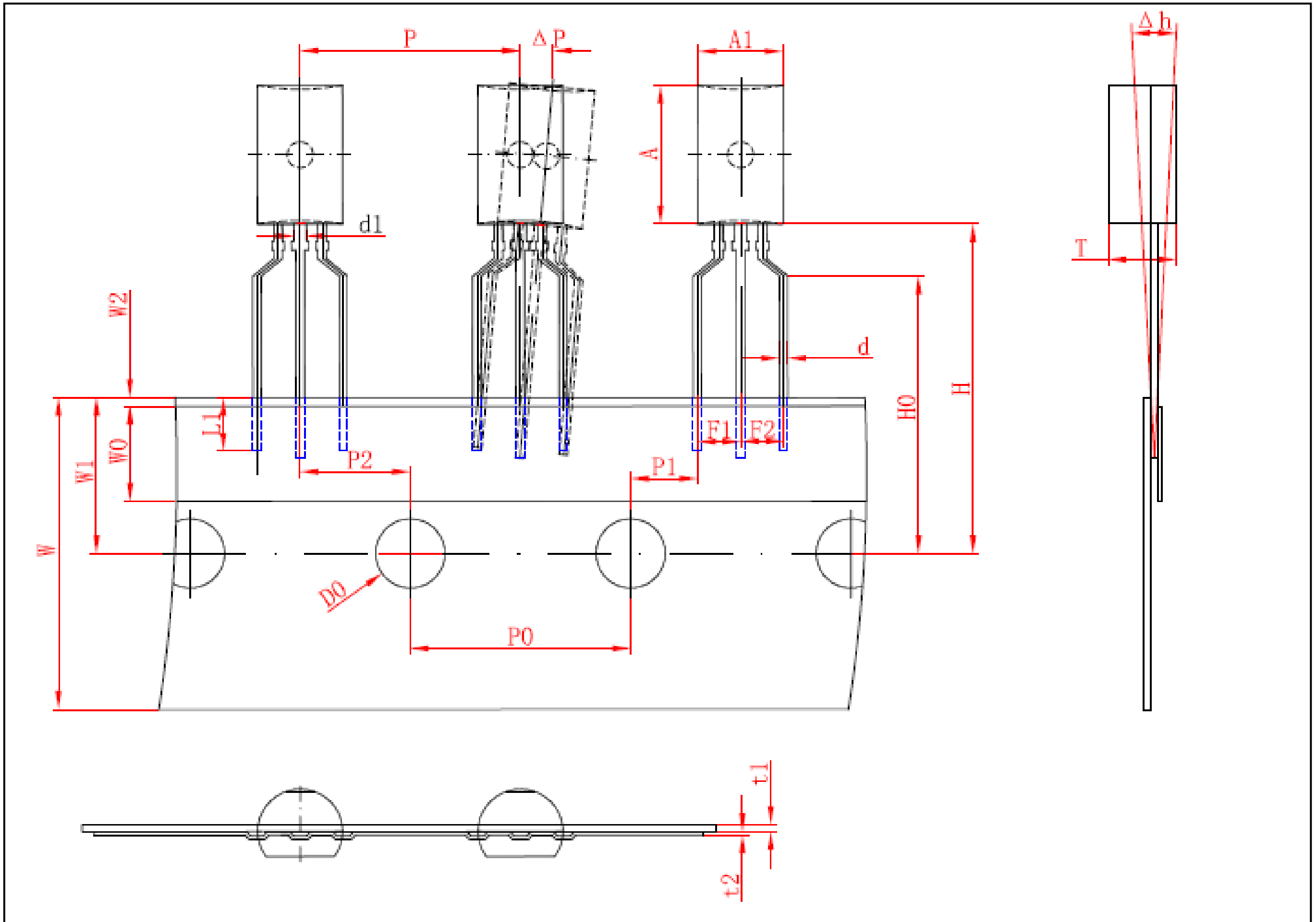








TO-92L Taping Outline

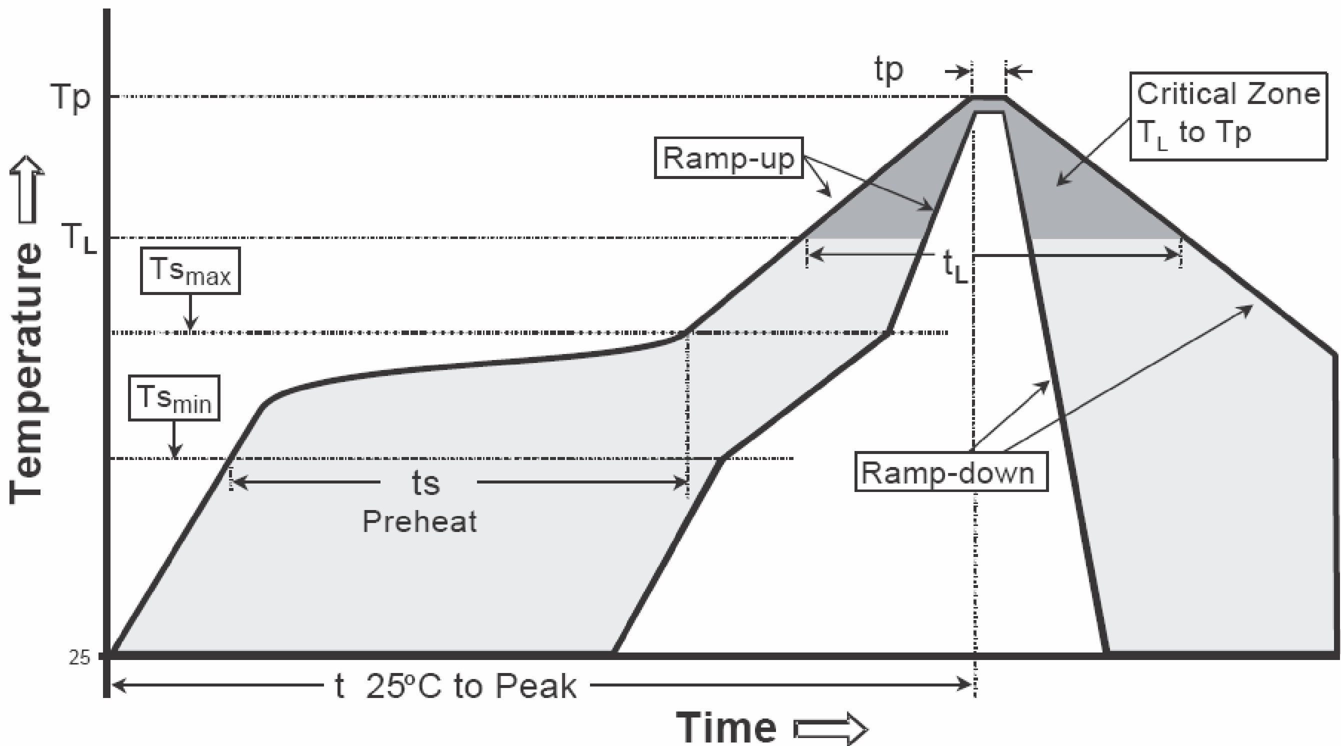


DIM	Item	Millimeters	
		Min.	Max.
A1	Component body width	4.70	5.10
A	Component body height	7.80	8.20
T	Component body thickness	3.70	4.10
d	Lead wire diameter	0.35	0.55
d1	Lead wire diameter 1	0.60	0.80
P	Pitch of component	12.40	13.00
P0	Feed hole pitch	12.50	12.90
P2	Hole center to component center	6.05	6.65
F1, F2	Lead to lead distance	2.20	2.80
△h	Component alignment, F-R	-1.00	1.00
W	Tape width	17.50	19.00
W0	Hole down tape width	5.50	6.50
W1	Hole position	8.50	9.50
W2	Hole down tape position	-	1.00
H	Height of component from tape center	19.00	21.00
H0	Lead wire clinch height	15.50	16.50
L1	Lead wire (tape portion)	2.50	-
D0	Feed hole diameter	3.80	4.20
t1	Taped lead thickness	0.35	0.45
t2	Carrier tape thickness	0.15	0.25
P1	Position of hole	3.55	4.15
△P	Component alignment	-1.00	1.00

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

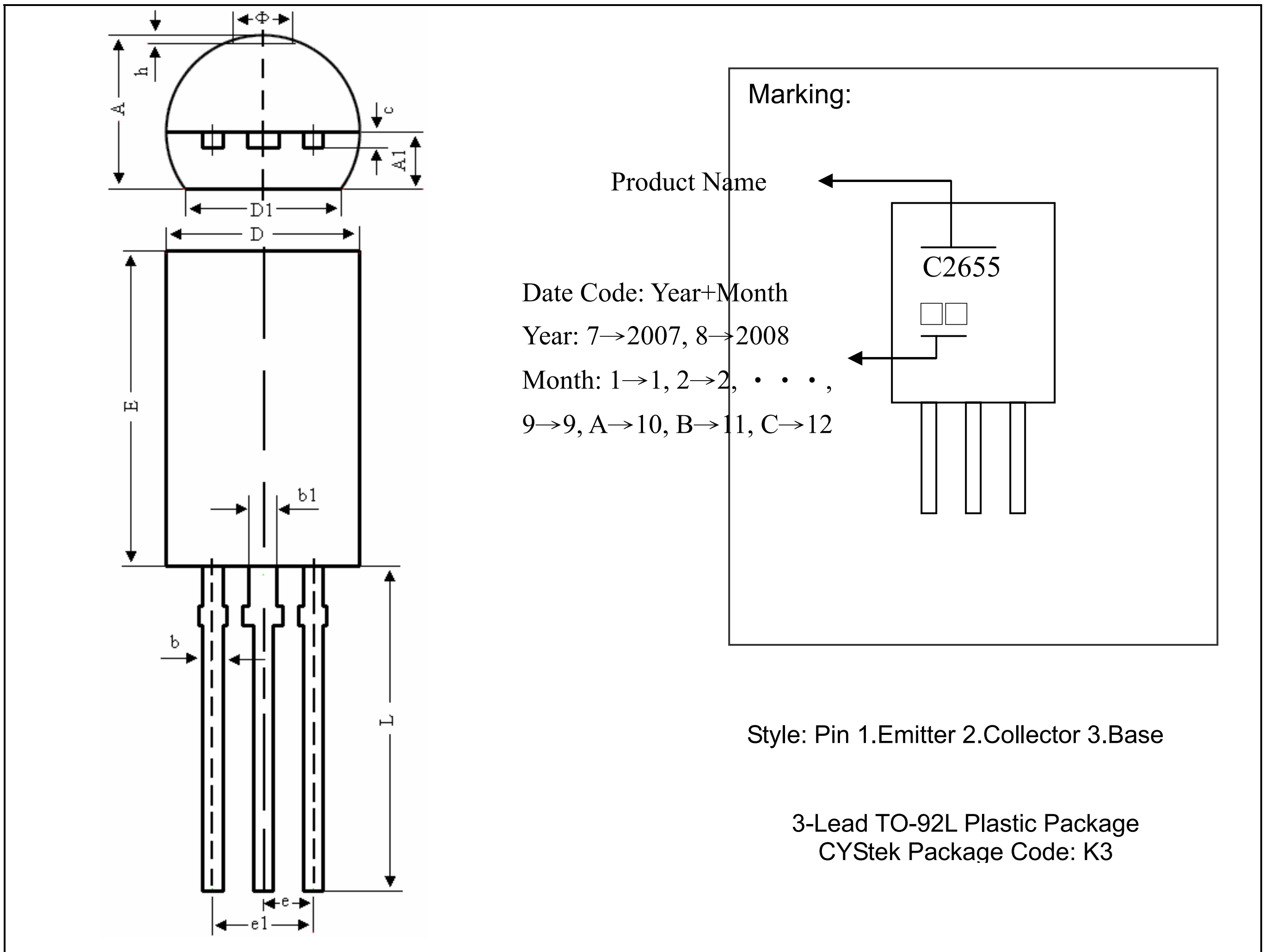
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(T_S min) −Temperature Max(T_S max) −Time(ts_{min} to ts_{max})	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (T_L) − Time (t_L)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(T_P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

TO-92L Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.146	0.161	3.700	4.100	E	0.307	0.323	7.800	8.200
A1	0.050	0.062	1.280	1.580	e	*0.05		*1.270	
b	0.014	0.022	0.350	0.550	e1	0.096	0.104	2.440	2.640
b1	0.024	0.031	0.600	0.800	L	0.543	0.559	13.800	14.200
c	0.014	0.018	0.350	0.450	φ	-	0.063	-	1.600
D	0.185	0.201	4.700	5.100	h	0.000	0.012	0.000	0.300
D1	0.157	-	4.000	-					

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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